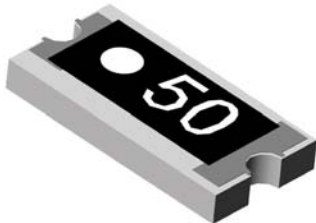




Surface Mount Termination 10 Watts, 50Ω



Description

The C10A50Z4 is high performance RoHS compliant Alumina (Al_2O_3) surface mount termination intended as a lower cost alternative to Aluminum Nitride (AlN) and Beryllium Oxide (BeO). The termination is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating 90 degree hybrid directional couplers, and for use in isolators.

General Specifications

Resistive Element	Thick film
Substrate	Alumina Ceramic
Terminal Finish	Matte Tin over Nickel
Operating Temperature	-55 to +125°C (see chart)

Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. **All dimensions in inches.**

Electrical Specifications

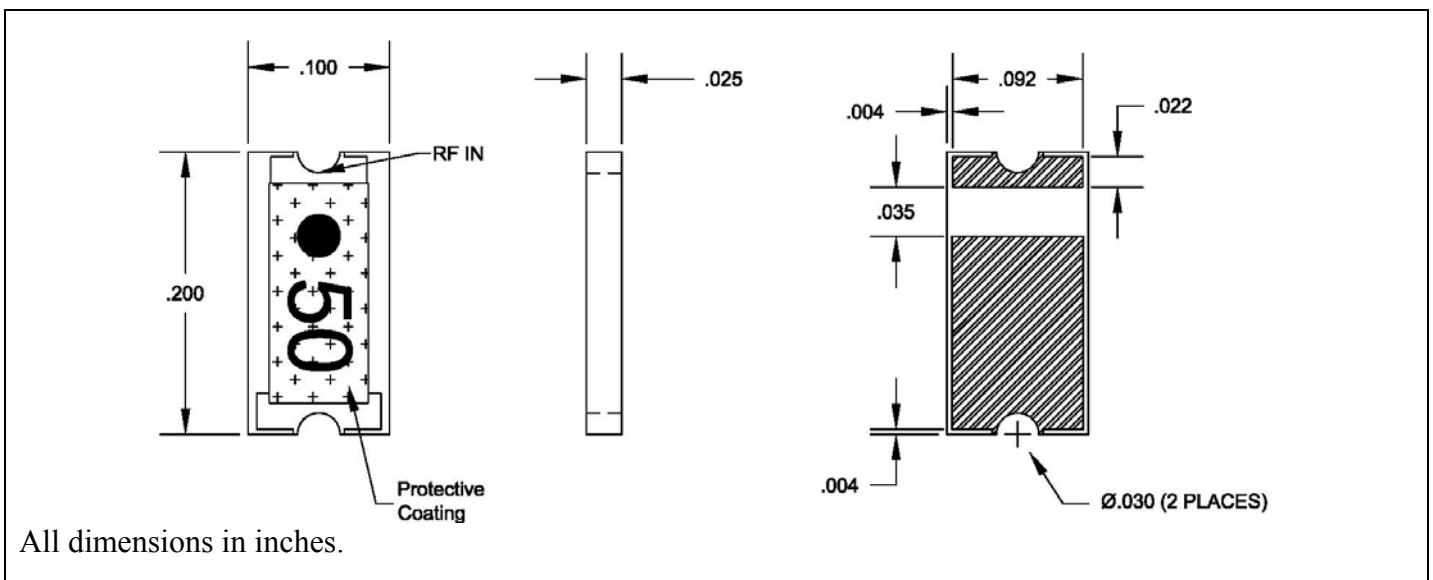
Resistance Value:	50 ohms, $\pm 2\%$
Power:	10 Watts
Frequency Range:	DC – 3.0 GHz
V.S.W.R.:	<1.25:1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change without notice**

Features:

- 10 Watts
- Lowest Cost
- RoHS Compliant
- Alumina Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Outline Drawing

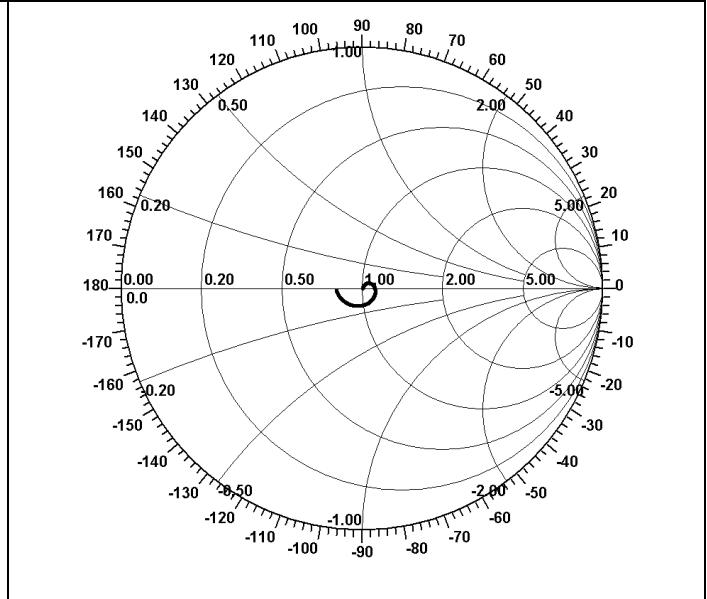
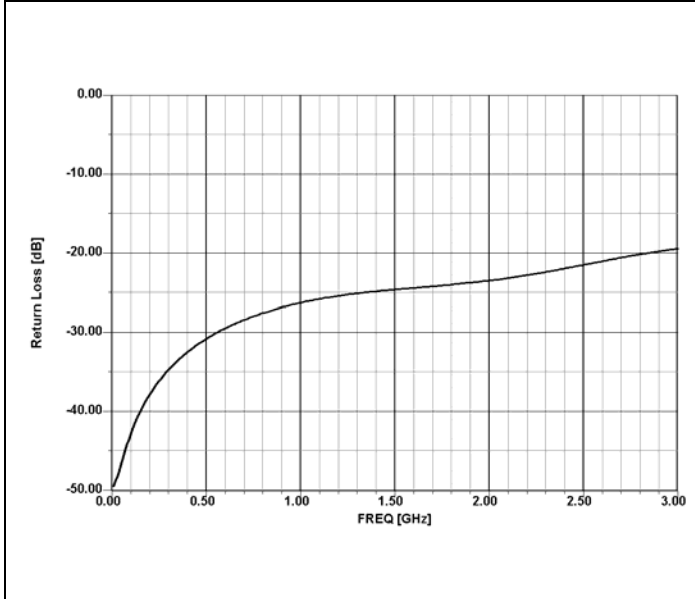


07/26/2006 Rev. B

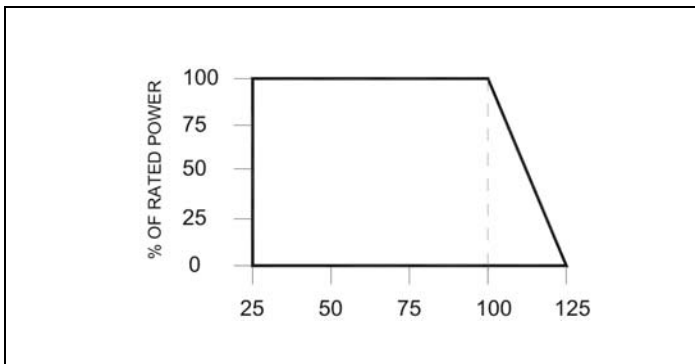




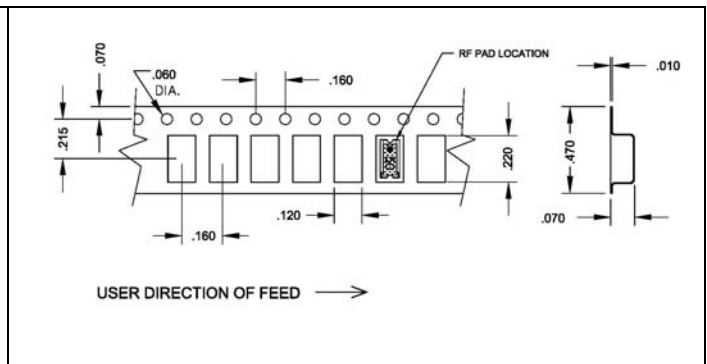
Typical Performance:



Power De-rating:



Tape & Reel:



Mounting Footprint and Procedure:

50 ohm line
0.092 [2.34]
0.025 [0.63]
0.035 [0.89]
Ø0.101 [Ø2.57]
2x 4-40 Screw Hole
Ø0.031 [Ø0.79]
0.060 [1.52]
0.250 [6.35]

Dimension given in inches [millimeters]
For best thermal performance the PCB should be soldered to the heat sink.

PC BOARD
HEATSINK
SOLDER PASTE
SOLDER FILLED VIA
SCREW (2 PLS.)

MOUNTING PROCEDURE

1. Drill thermal vias through PCB and fill with solder.
2. To ensure good thermal connectivity to heat sink, which is critical for proper operation drill and tap heatsink and mount PCB to heat sink using screws.

